

<b>Notice of References Cited</b>	Application/Control No. 09/832,884	Applicant(s)/Patent Under Reexamination DANZIGER ET AL.	
	Examiner Evan Pert	Art Unit 2829	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-5,623,394	04-1997	Sherif et al.	361/705
	C	US-			
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	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Shaukatullah et al., "Thermal Enhancement of Flip-Chip Packages with Radial-Finger-Contact Spring", May 1995, IEEE 45 th Electronic Components and Technology Conference, pages 865-871.
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.